

ON Semiconductor



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Semiconductor Technology Group
Issuing Division: ON SEMICONDUCTOR

PRODUCT BULLETIN
Generic Copy

29-JUN-2000

Subject: ON Semiconductor PRODUCT BULLETIN 10192

TITLE: SMC BARE COPPER CLIP CONVERSION

EFFECTIVE DATE: 30-Jun-2000

AFFECTED CHANGE CATEGORIES

AFFECTED PRODUCT DIVISIONS

* BIPOLAR DISCRETES PRODUCTS DIV

ADDITIONAL RELIABILITY DATA: None
REFERENCE: Contact Sales Office ()

SAMPLES: No
REFERENCE: Contact Sales Office ()

For any questions concerning this notification:
REFERENCE: Contact Sales Office (KEVIN KELLER)

DISCLAIMER

ON SEMICONDUCTOR CONSIDERS THIS CHANGE APPROVED UNLESS SPECIFIC
CONDITIONS OF ACCEPTANCE ARE PROVIDED IN WRITING. TO DO SO, CONTACT
YOUR LOCAL ON SEMICONDUCTOR SALES OFFICE.

DO NOT REPLY TO THIS MESSAGE.
GPCN FORMAT: CUSTOMER

DESCRIPTION AND PURPOSE

On all the SMC packages, the clip forming the electrical connection between the top surface of the die and leadframe will change from nickel plated copper to bare copper only. This is a continuous improvement change that will enhance solder wetting to the clip.

AFFECTED DEVICE LIST

PART

1.5SMC10AT3
1.5SMC12AT3
1.5SMC13AT3
1.5SMC15AT3
1.5SMC16AT3
1.5SMC18AT3
1.5SMC20AT3
1.5SMC22AT3
1.5SMC24AT3
1.5SMC27AT3
1.5SMC30AT3
1.5SMC33AT3
1.5SMC36AT3
1.5SMC39AT3
1.5SMC43AT3
1.5SMC47AT3
1.5SMC51AT3
1.5SMC56AT3
1.5SMC6.8AT3
1.5SMC62AT3
1.5SMC68AT3
1.5SMC7.5AT3
1.5SMC75AT3
1.5SMC8.2AT3
1.5SMC82AT3
1.5SMC91AT3
1SMC10AT3
1SMC12AT3
1SMC13AT3
1SMC14AT3
1SMC15AT3
1SMC16AT3
1SMC17AT3
1SMC18AT3
1SMC20AT3
1SMC22AT3
1SMC24AT3
1SMC26AT3
1SMC28AT3
1SMC30AT3
1SMC33AT3
1SMC36AT3
1SMC40AT3
1SMC43AT3
1SMC45AT3
1SMC48AT3
1SMC5.0AT3
1SMC51AT3
1SMC54AT3
1SMC58AT3
1SMC6.0AT3
1SMC6.5AT3
1SMC60AT3

AFFECTED DEVICE LIST

PART

1SMC64AT3
1SMC7.0AT3
1SMC7.5AT3
1SMC70AT3
1SMC75AT3
1SMC78AT3
1SMC8.0AT3
1SMC8.5AT3
1SMC9.0AT3
MBRS320T3
MBRS330T3
MBRS340T3
MBRS360T3
MURS320T3
MURS340T3
MURS360T3
SBRS5652T3
SBRS8340T3